

M1FL40U

Fast Recovery Diodes

400V, 1.5A

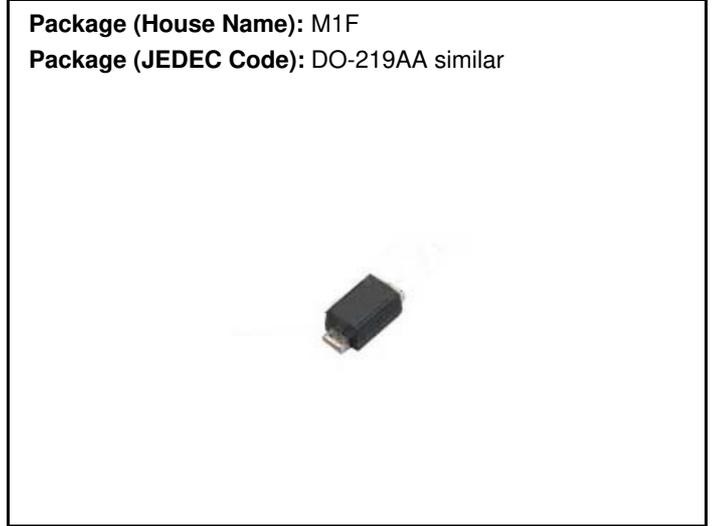
Feature

- Small SMD
- High Recovery Speed
- Available for automotive use
- Pb free terminal
- RoHS:Yes

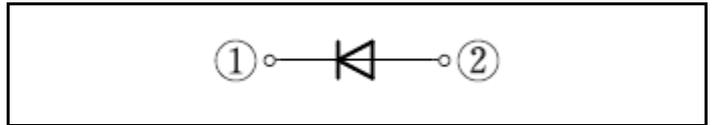
OUTLINE

Package (House Name): M1F

Package (JEDEC Code): DO-219AA similar



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | Unit |
|---------------------------------|--------------------|---|------------|------|
| Storage temperature | T _{stg} | | -55 to 175 | °C |
| Junction temperature | T _j | | -55 to 175 | °C |
| Repetitive peak reverse voltage | V _{RRM} | | 400 | V |
| Average forward current | I _{F(AV)} | 50Hz sine wave, Resistance load, T _c =139°C | 1.5 | A |
| Average forward current | I _{F(AV)} | 50Hz sine wave, Resistance load, T _l =135°C | 1.5 | A |
| Average forward current | I _{F(AV)} | 50Hz sine wave, Resistance load, On alumina substrate, T _a =54°C ※ | 1 | A |
| Average forward current | I _{F(AV)} | 50Hz sine wave, Resistance load, On glass-epoxy substrate, T _a =25°C ※ | 0.78 | A |
| Surge forward current | I _{FSM} | 50Hz sine wave, Non-repetitive 1 cycle, Peak value, T _j =25°C | 30 | A |
| Surge forward current | I _{FSM1} | t _p =1ms, Sine wave, Non-repetitive, Peak value, T _j =25°C | 90 | A |

※ :See the original Specifications

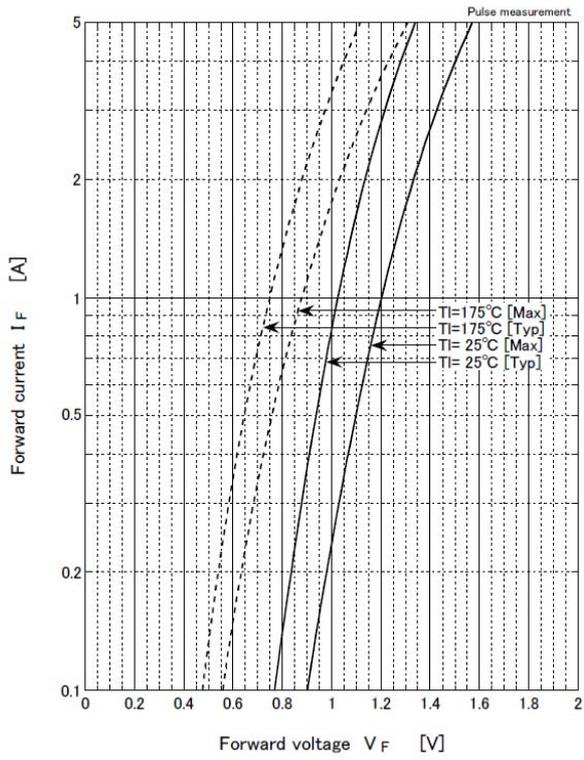
Electrical Characteristics (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | | | Unit |
|-----------------------|---------------|---|---------|-----|-----|---------------|
| | | | MIN | TYP | MAX | |
| Forward voltage | V_F | $I_F=1A$, Pulse measurement | | | 1.2 | V |
| Reverse current | I_R | $V_R=400V$, Pulse measurement | | | 10 | μA |
| Reverse recovery time | t_{rr} | $I_F=0.5A$, $I_R=1.0A$, $0.25I_R$ | | | 25 | ns |
| Total capacitance | C_t | $f=1MHz$, $V_R=10V$ | | 11 | | μF |
| Thermal resistance | $R_{th(j-c)}$ | Junction to case | | | 18 | $^{\circ}C/W$ |
| Thermal resistance | $R_{th(j-l)}$ | Junction to lead | | | 20 | $^{\circ}C/W$ |
| Thermal resistance | $R_{th(j-a)}$ | Junction to ambient, On alumina substrate ※ | | | 108 | $^{\circ}C/W$ |
| Thermal resistance | $R_{th(j-a)}$ | Junction to ambient, On glass-epoxy substrate ※ | | | 186 | $^{\circ}C/W$ |

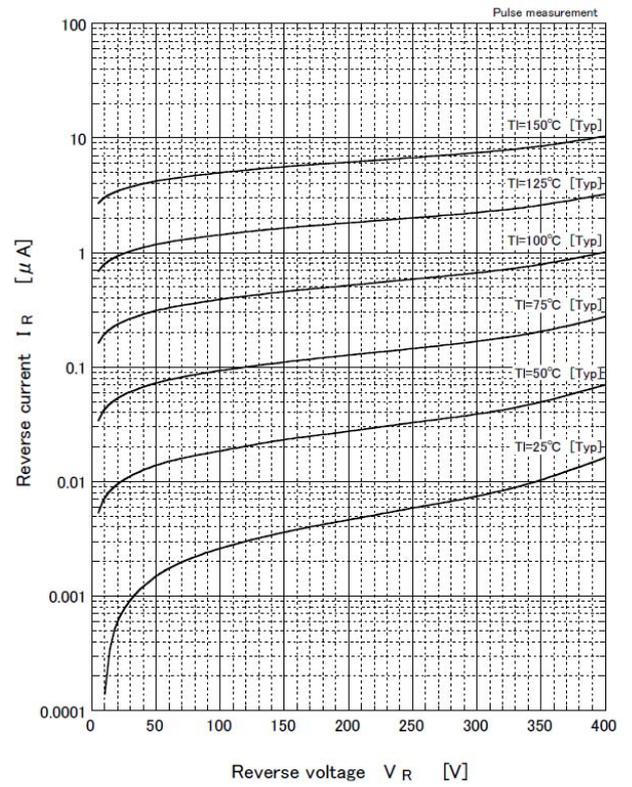
※ :See the original Specifications

CHARACTERISTIC DIAGRAMS

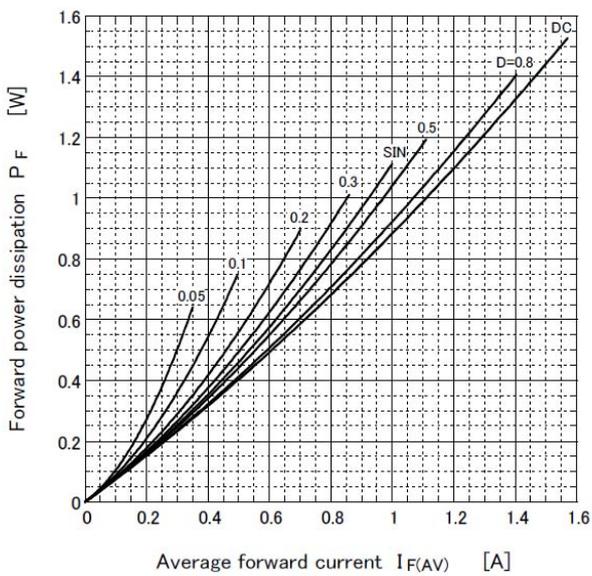
Forward voltage



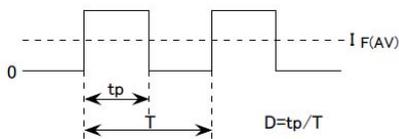
Reverse current



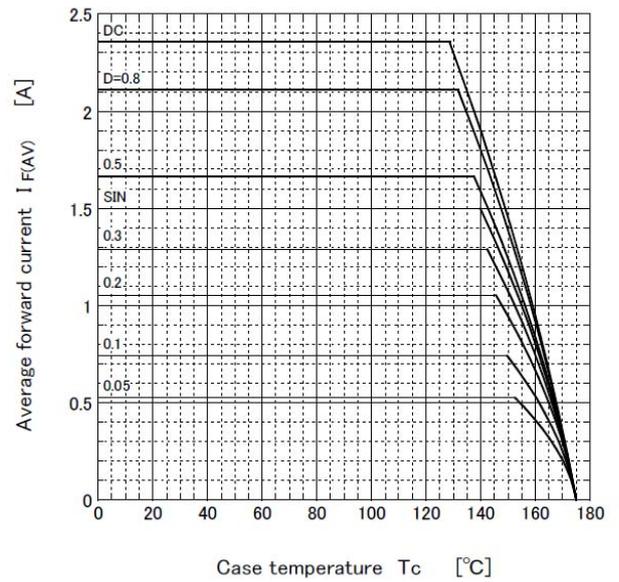
Forward power dissipation



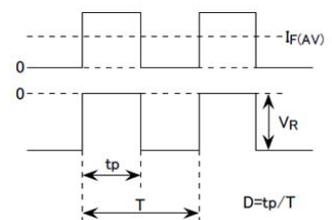
● $T_J = 175^\circ\text{C}$



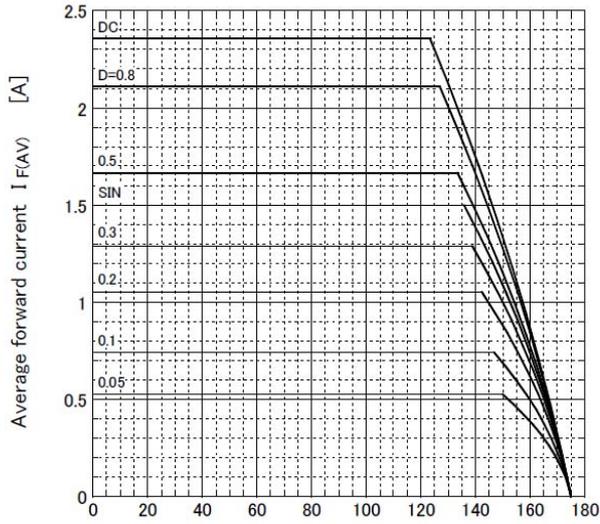
Derating curve



● $V_R = 400\text{V}$
R-load
Free in air

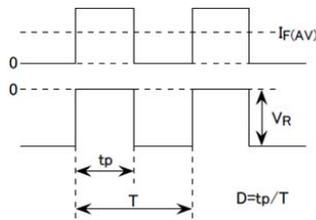


Derating curve

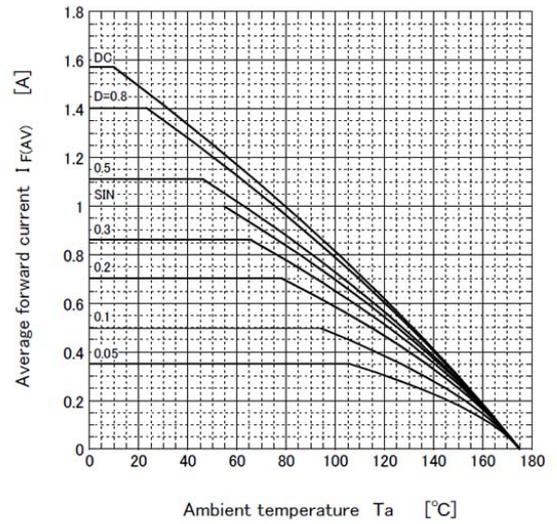


● $V_R = 400V$
R-load
Free in air

Lead temperature T_l [°C]



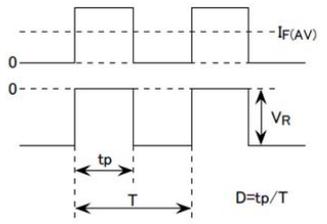
Derating curve



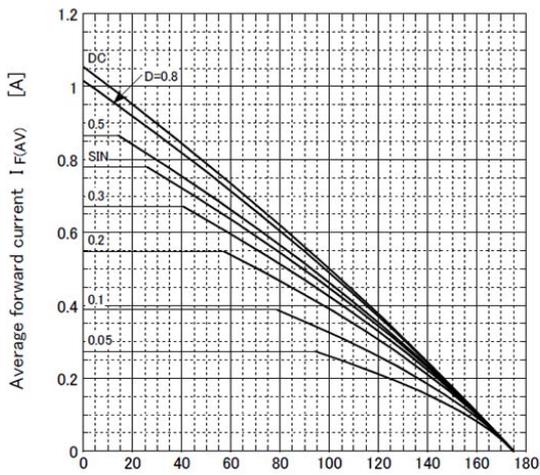
● $V_R = 400V$
R-load
Free in air

● Substrate detail

| | |
|---------------------|---------------------|
| Type | Alumina |
| Size | 1 inch ² |
| Thickness | 0.64mm |
| Conductor thickness | 20 μm |
| Pattern area | 43.4mm ² |



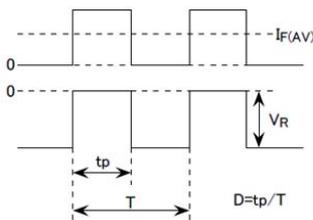
Derating curve



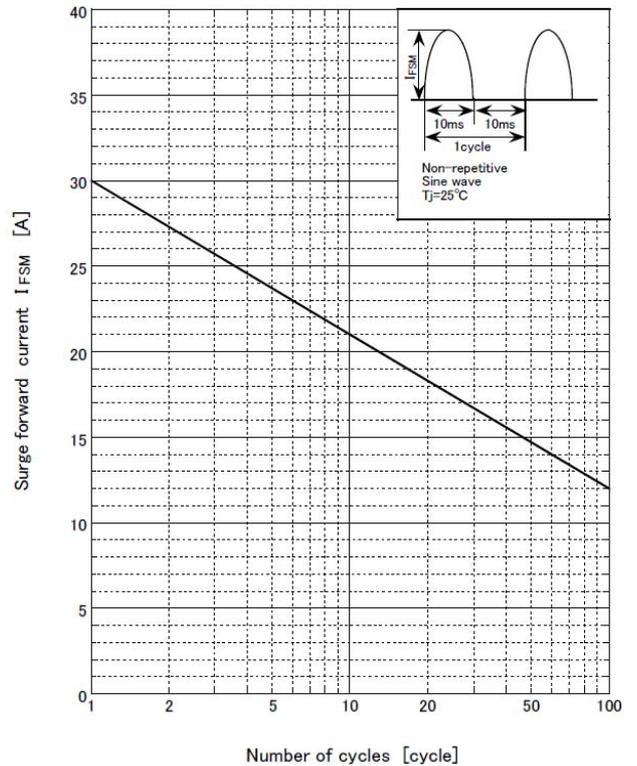
● $V_R = 400V$
R-load
Free in air

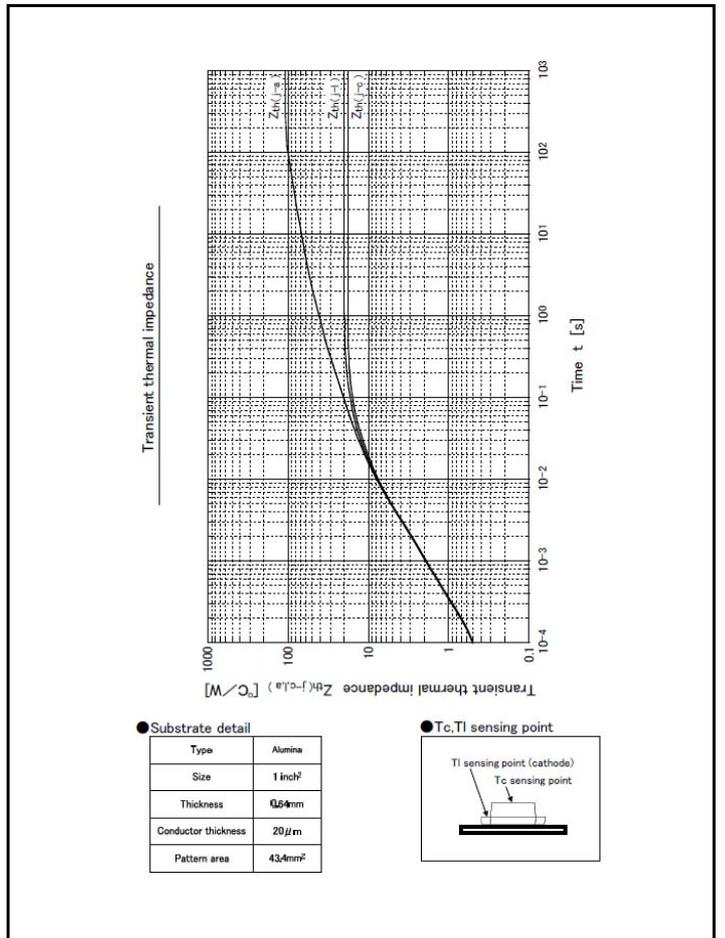
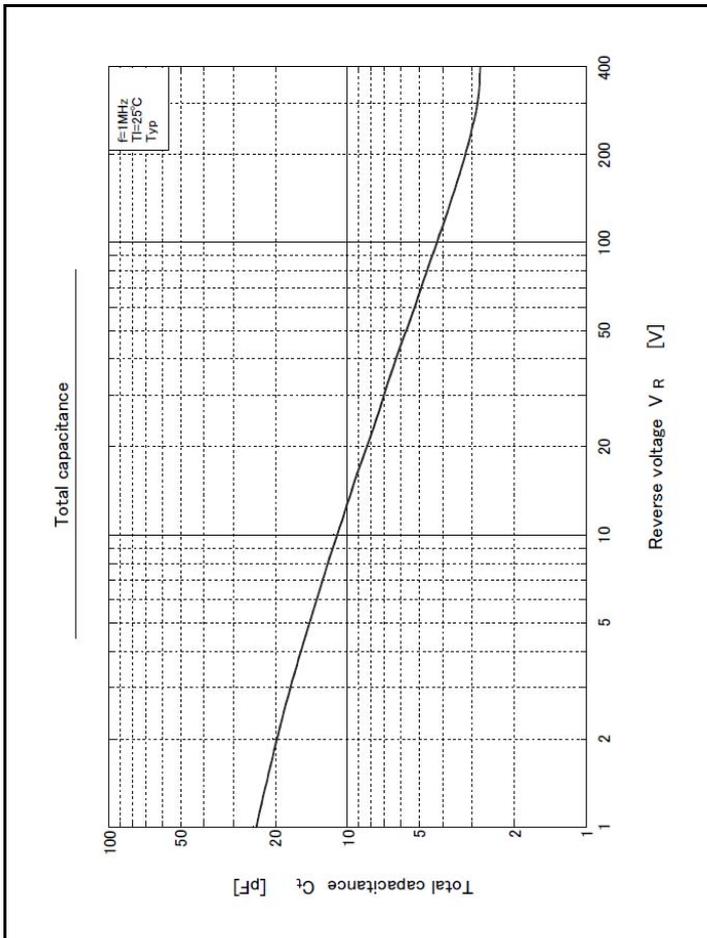
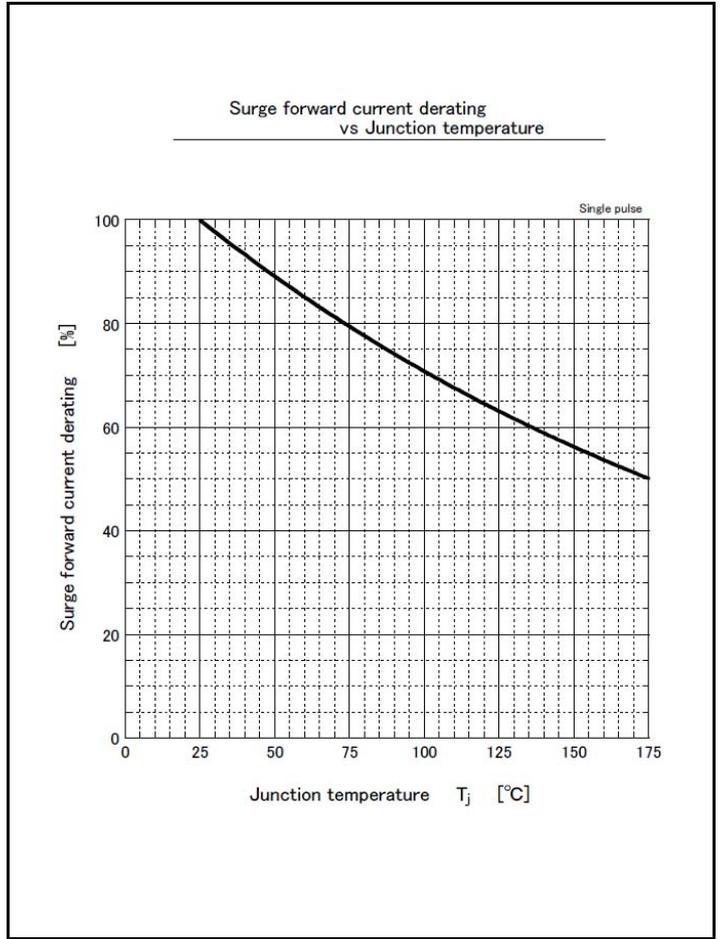
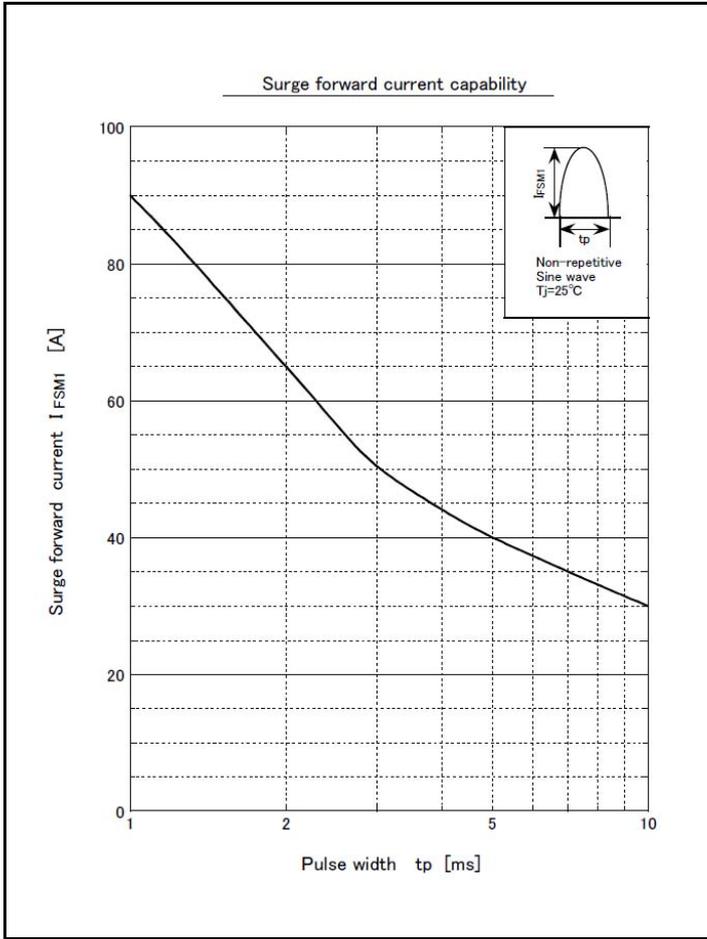
● Substrate detail

| | |
|---------------------|---------------------|
| Type | Glass/epoxy |
| Size | 1 inch ² |
| Thickness | 1.8mm |
| Conductor thickness | 35 μm |
| Pattern area | 43.4mm ² |

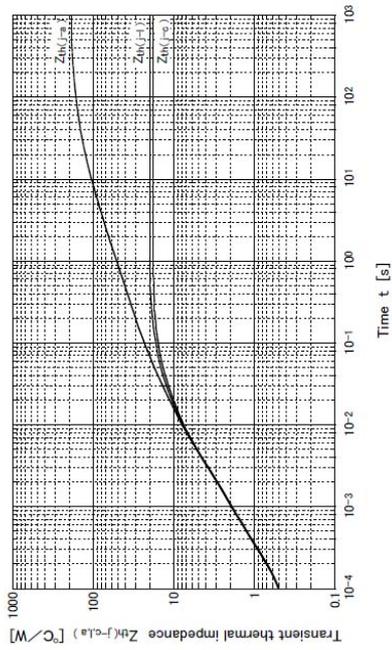


Surge forward current capability





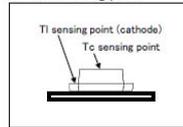
Transient thermal impedance



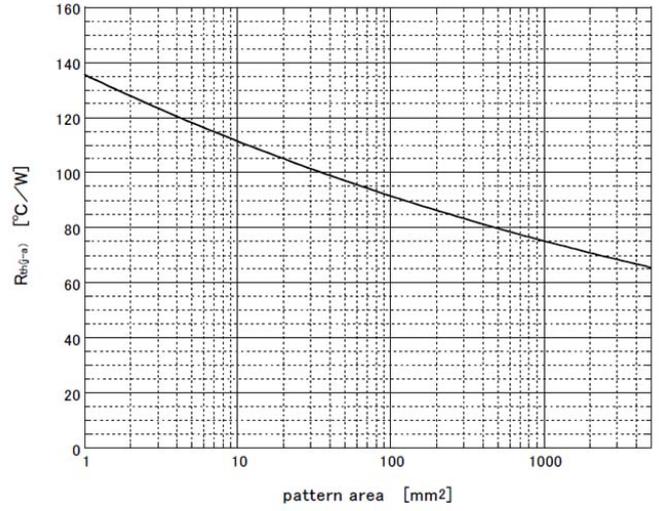
● Substrate detail

| | |
|---------------------|---------------------|
| Type | Glass-epoxy |
| Size | 1 inch ² |
| Thickness | 1.6mm |
| Conductor thickness | 35 μm |
| Pattern area | 43.4mm ² |

● Tc, Tl sensing point



$R_{th(j-a)}$ - pattern area

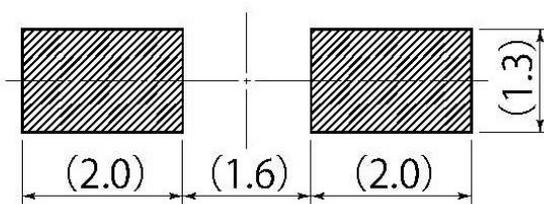
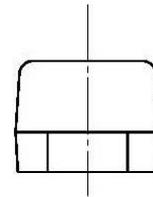
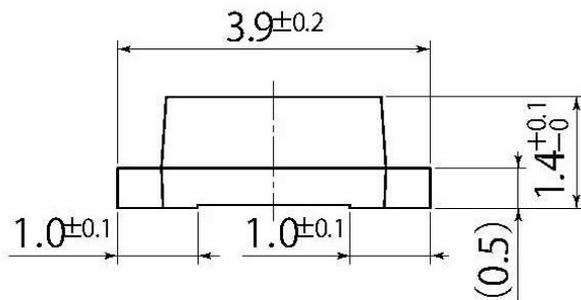
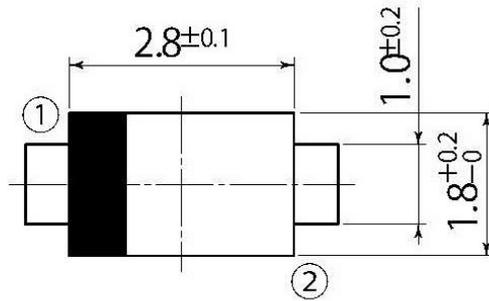


● Substrate detail

| | |
|---------------------|---------------------|
| Type | Glass-epoxy |
| Size | 1 inch ² |
| Thickness | 1.6mm |
| Conductor thickness | 35 μm |

B2

| | |
|------------|------------------|
| JEDEC Code | DO-219AA similar |
| JEITA Code | — |
| House Name | M1F |



Referential Soldering Pad

- Optimize soldering pad to the board design and soldering condition.

Notes

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